

Request for Proposals (RFP)

The provision or supply of Manufacturing of the Fingerprint Recognition Device to CSIR

RFP No - 1028/16/09/2022

Date of Issue	Thursday, 01 September 2022		
	Monday, 05 September 2022 at 11:00		
	Venue: CSIR Pretoria		
Briefing session	Building 17B Boardroom 1st Flo	oor	
	Meiring Naude Road		
	Brummeria		
Closing Date	Friday, 16 September 2022 at 16:30		
	Electronic submission: tender@csir.co.za		
Disease	Mail size is limited to 25MB, if the document exceeds this		
Place	limit, please send multiple emails.		
	Cloud submissions will not be accepted		
Enquiries	Strategic Procurement Unit		
CSIR business hours	08h00 – 16h30 CSIR business hours		
Category	Professional		

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SECTION A - TECHNICAL INFORMATION

1 INTRODUCTION

The Council for Scientific and Industrial Research (CSIR) is one of the leading scientific research and technology development organisations in Africa. In partnership with national and international research and technology institutions, CSIR undertakes directed and multidisciplinary research and technology innovation that contributes to the improvement of the quality of life of South Africans. The CSIR's main site is in Pretoria while it is represented in other provinces of South Africa through regional offices.

2 BACKGROUND

The CSIR designed a prototype Fingerprint recognition Device which is a standalone, 3D printed handheld and Lithium-Ion battery operated Device. The Device contains the following user interfaces: digital camera, button controls, LCD screen, ethernet port, USB port (micro port) and an LED. The Device incorporates a Raspberry Pi 4 (PI) board and four (4) custom designed Printed Circuit Boards (PCB's) i.e., Button PCB board, LED PCB board, Pi shield PCB board and the Screen adapter PCB board. The Device perform identification and verification of a person by capturing a fingerprint from a person and from a paper using the digital camera interface.

The CSIR requires service to manufacture the Fingerprint Recognition Device in accordance to the provided specifications (Procurement and Sourcing of components, PCB manufacturing and assemblies, 3D enclosure printing, assembling the complete Device and Device acceptance testing) and also to design and manufacture the power supply module (power path switching, battery charging and battery level monitoring) to power the Device.

Definitions:

- a) **Device:** Fingerprint Recognition device without the Power Supply Module
- b) Fully Assembled device: Fingerprint Recognition Device with the Power Supply Module

3 INVITATION FOR PROPOSAL

Proposals are hereby invited for the supply of Manufacturing of the Fingerprint Recognition Device to the CSIR's. The full scope of work will at first include quoting the design of the power supply module for the Device, manufacturing and assembling the Device from existing designs and sourcing and procuring the components required.

The CSIR requires service to manufacture the Fingerprint Recognition Device in accordance to the provided specifications (Procurement and Sourcing of components, PCB manufacturing and assemblies, 3D enclosure printing, and Device acceptance testing) and also to design and manufacture the power supply module (power path switching, battery charging and battery level monitoring) for the Device.

4 PROPOSAL SPECIFICATION

All proposals are to be submitted in a format specified in this enquiry (if applicable).

Project Specifications

4.1 Fingerprint Recognition Device: PCB Manufacturing and Procurement of Components

Description: Manufacturing of the custom PCB's and procurement of the components

- **4.1.1. Sub-requirement 1:** PCB population must be of Surface Mount Devices (SMD)
- **4.1.2. Sub-requirement 2:** PCB Quantity must be 10 per each custom-designed PCB
- **4.1.3. Sub-requirement 3:** PCB Manufacturing compliant must be compliant with IPC Class II specification
- **4.1.4. Sub-requirement 4:** PCB Complexity: As per the binary files (Gerber and drill files) of the four (4) custom-designed Printed Circuit Boards (PCB's) subjected to Non-Disclosure Agreement (NDA). The briefing session will be used to present the technical specifications of the PCB designs of the Device.
- **4.1.5. Sub-requirement 5:** Quality Assurance on PCB's (IPC Class II specification)
- **4.1.6. Sub-requirement 6:** Source, procure and inspect components as per the provided Bill of Material (BOM). The BOM file will be shared to attendees during the briefing session.

4.2 Fingerprint Recognition Device: 3D printing of the enclosure

Description: 3D printing of the Device enclosure

- **4.2.1. Sub-requirement 1:** The enclosure must be of SLS prototype
- **4.2.2. Sub-requirement 2:** The enclosure material type must be of minimum quality SLS Polyamide (e.g., Nylon 11 powder)
- **4.2.3. Sub-requirement 3:** The device enclosure must be printed according to the provided STEP files and their respective quantities per Device:
 - i. 1 x Body Fingerprint Scanner Button
 - ii. 1 x Body Fingerprint Scanner Face
 - iii. 1 x Body Fingerprint Scanner Top
 - iv. 1 x Carriage PCB Buttons
 - v. 1 x Catch Screen
 - vi. 1 x Camera Holder
 - vii. 1 x Lid Button
 - viii. 2 x Carriage Button
 - ix. 5 x Button Hat
- **4.2.4. Sub-requirement 4:** The enclosure must have a quality assurance on the printed 3D structures
- 4.2.5. Sub-requirements 5: Device enclosure complexity: As per supplied enclosure specification subjected to Non-Disclosure Agreement (NDA) The briefing session will be used to present Device enclosure designs. The dimensions and 3D enclosure files will be shared to attendees during the briefing session.
- **4.2.6. Sub-requirement 6:** The enclosure color must be black.
- **4.3 Fingerprint Recognition Device:** Manufacturing and Assembly of the Device (PCB Assemblies)

Description: The fully assemble Device must be able to perform recognition of fingerprints

- **4.3.1.** Sub-requirement 1: Assemble all the Device sub-modules (requirement 4.1, requirement 4.2 and requirement 4.4) inside the enclosure (requirement 4.3) to have a fully assembled Fingerprint Recognition Device The briefing session will be used to present the technical specifications of the PCB board circuits, and the system integration procedure for the Device.
- 4.3.2. Sub-requirement 2: IPC Class II specification
- **4.4 Fingerprint Recognition Device:** Design and Manufacturing of the Power Supply Module

The following are the technical requirements for the power supply module of the Device.

4.4.1. PCB Design and Manufacturing:

Description: The power supply module PCB must be of surface mount technology and be able to fit in the dimensions of the Device's bottom handle part.

- **4.4.1.1 Sub-requirement 1:** Power supply module PCB is of surface mount with a minimum of double-layer PCB type
- **4.4.1.2 Sub-requirement 2:** PCB Dimensions: 33mm x 33mm x 5mm(LxWxH)
- **4.4.1.3 Sub-requirement 3:** PCB Mounting: Corner mounted with (6mm x 3mm) head screws measured 28mm from the centre of the screw holes.
- **4.4.1.4 Sub-requirement 4:** PCB Complexity: Solder Masking, minimum of double-layer and silk screening.
- **4.4.1.5 Sub-requirement 5:** Quality: IPC Class II specification
- **4.4.1.6 Sub-requirement 6:** micro-USB connector positioned to fit as described in the Step file (body fingerprint scanner Bottom Step file).

4.4.2. Power Supply Sources:

Description: The power supply module must be able to be powered from the Lithium-lon battery and a 5V/2A DC source.

- **4.4.2.1 Sub-requirement 1:** The power supply module must be able to be powered by a Lithium-Ion Battery with maximum dimensions of 70mm x 60mm x 10mm. (LxWxH)
- **4.4.2.2 Sub-requirement 2:** The power supply module must be able to be powered by the DC Source rated at 5V/2A with a micro-USB output connector.
- **4.4.2.3 Sub-requirement 3:** The power supply module must have a status indicator that shows when the battery is charging and when is fully charged when the 5V DC source is plugged in.

4.4.3. Power path Switching:

Description: The power supply module must incorporate a powerpath controller for power switchover between a battery and a 5V DC source when powering the Device.

- **Sub-requirement 1:** The Device must power ON when the Lithium-Ion Battery is plugged into the power supply module.
- **4.4.3.2 Sub-requirement 2:** The Device must power on from the DC source (5V/2A) when the source is plugged into the power supply module even when the battery is present.
- **4.4.3.3 Sub-requirement 3:** The power supply module must be able to charge the battery while powering the Device from the 5V DC source.

- **4.4.3.4 Sub-requirement 4:** The power module circuit must be able to track the Lithium-Ion battery level and communicated this through an I2C interface.
- **4.4.3.5 Sub-requirement 5:** The power supply module must incorporate a battery charger capability that will charge the battery when the input power is from the 5V DC source.

4.4.4. Documentation

Description: The power supply module must be supplied with documentation.

- **4.4.4.1 Sub-requirement 1:** The power supply module shall contain datasheets for all components including the battery, PCB binary files, and schematic circuit diagrams.
- 4.5 Fingerprint Recognition Device: System Acceptance Testing

Description: Perform the following system acceptance tests to the expected results as outlined in table 1 below.

4.5.1. Sub-requirement 1: Test report outlining the test cases outcome results.

Table 1: Fingerprint Recognition Device acceptance testing

Test Case ID	Scenario	Test Case	Pre- conditions	Expected Results
CaseID1			Battery and power supply module must be connected to the Device	a) The Device must power ON when only the Battery is connected to the power supply module.
	Power ON and OFF	Power Supply Module test	DC Source and power supply module must be connected to the Device	b) The Device must power ON when the DC source is connected to the power supply module
			DC Source, Battery and power supply module must be connected to the Device	 c) The power supply module must be able to charge the battery while powering the Device from the DC source. d) The power supply module must be able to

					provide a power switchover between the battery and charger to the Device.
CaseID2	Button Interfaces	Buttons functions on the Device tests	be loaded on the Device Raspberry PI	a.1 b)	Button 1 (Power Button): To trigger the device ON and OFF functionalities. The Device from OFF state, MUST switch ON when Button 1 is pressed. 1) To switch the Device OFF from ON state, when Button 1 is pressed and hold for about 3 seconds, the Device must switch OFF. Button 2 (Left Button): When pressed, the bottom left block from the screen must be highlighted Button): When pressed, the bottom middle block from the screen must be highlighted Button 4 (Right Button): When pressed, the bottom right block from the screen must be highlighted Button 5 (Gun-Trigger Button): When pressed, the bottom right block from the screen must be highlighted
CaseID3	Ethernet connectivity	Detecting Device IP address	Fully Assembled Device connected to a network	а)	Device IP address will be displayed on the screen

			port via an ethernet cable Device Test application to be loaded on the Device Raspberry PI	
CaseID4	GPS Hardware triggering	Detecting Device GPS location	Fully Assembled Device Device Test application to be loaded on the Device Raspberry PI	a) Device GPS coordinates (GPS fix) displayed on the screen.
CaseID5	Camera triggering	Triggering Device Camera and illumination LED	Fully Assembled Device Device Test application to be loaded on the Device Raspberry PI	 a) Button 4 (Right Button): When pressed, a message will display on LCD to open the camera. a.1) When pressed again, the camera must open, and the illumination LED must switch ON.

Expected Deliverables

Table 2: Expected deliverables

Device		
	Description	Quantity
a) Fully Assembled,	Fingerprint Recognition	
Functional and	Devices	10
Tested Fingerprint		
Recognition Devices		
b) Power Supply Module	Documentation for the	Set
documentation	design of the power supply	
	module	

Accessories	Description	Quantity
a) Lithium-Ion Battery	Battery for the Power Supply	20
	module	
b) 5V/2A micro-USB	DC source for the Power	10
Power Source	Supply Module	

5 FUNCTIONAL EVALUATION CRITERIA

5.1 The evaluation of the functional/technical detail of the proposal will be based on the following criteria:

Technical Criteria's

Table 3: Technical evaluation criteria's

Requirement 4.3	The fully assemble Device must be able to perform recognition of fingerprints			
	Technical Criteria	Verification Test	Outcome – Not Met	Outcome - Met
Sub-requirement 4.3.1	Assemble all the Device sub-modules (requirement 4.1,	Power – The Device must switch ON and OFF	0	100
	requirement 4.2 and requirement 4.4) inside the enclosure (requirement 4.3)	Buttons – All buttons are functional when pressed	0	100
	to have a fully assembled Fingerprint Recognition Device. Load the executable Test	Camera – When button 4 or Gun triggered button is pressed, the camera must open, and the illumination LED must switch ON.	0	100
	application. Fully assembled Device must be connected to a network port via an ethernet cable.	GPS - Device GPS coordinates (GPS fix) must display on the screen or stored locally on the database.	0	100

		Ethernet - Device	0	100
		IP address must		
		display on the screen		
Sub-requirement	IPC Class II	Supplier must	0	100
4.3.2	specification	provide a		
		manufacturing report or certificate		
		for quality		
		assurance		
	.	1 000		
Requirement 4.1	Manufacturing of the components	e custom PCB's and բ	procurement of the	
	Technical Criteria	Verification Test	Outcome - Not	Outcome
			met	Met
Sub-requirement	PCB population	Inspect the PCB of	0	100
4.1.1	must be of Surface Mount Devices	any through-hole components		
	(SMD).	Components		
Sub-requirement	PCB Quantity	Count the custom	0	100
4.1.2	must be 10 per	PCB's		
	each custom designed PCB.			
Sub-requirement	PCB	Supplier must	0	100
4.1.3	Manufacturing	provide a		
	compliant must be	manufacturing		
	compliant with IPC Class II	report or certificate for quality		
	specification.	assurance		
Sub-requirement	PCB Complexity:	Signing of the	0	100
4.1.4	As per the binary	NDA and the		
	files (Gerber and drill files) of the	Declaration Form		
	four (4) custom			
	designed Printed			
	Circuit Boards			
	(PCB's) subjected			
	to Non-Disclosure			
	Agreement (NDA). - The briefing			
	session will be			
	used to present the			
	technical			
	specifications of			
	the PCB designs of the Device.			
Sub-requirement	Quality Assurance	Supplier must	0	100
4.1.5	on PCB's (IPC	provide a		
	Class II	manufacturing		
	specification)	report or certificate		1

		for quality assurance		
Sub-requirement 4.1.6	Source, procure and inspect components as per the provide Bill of Material (BOM).	Go through the BOM list and check that each component is procured	0	100
Paguiroment 4.2	2D printing of the D	ovice enclosure		
Requirement 4.2	3D printing of the De Technical Criteria	Verification test	Outcome Not Met	Outcome met
Sub-requirement 4.2.1	The enclosure must be of SLS prototype.	Supplier must provide the manufacturing report or certification indicating the SLS specifications	0	100
Sub-requirement 4.2.2	The enclosure material type must be of minimum quality SLS Polyamide (e.g., Nylon 11 powder).	Supplier must provide the manufacturing report or certification indicating the SLS specifications	0	100
Sub-requirement 4.2.3	The Device enclosure must be printed according to the provided STEP files and their respective quantities.	Check the 3D printed structures according to the provided files and their respective quantities	0	100
Sub-requirement 4.2.4	The enclosure must have a quality assurance on the printed 3D structures.	Supplier must provide the manufacturing report or certification indicating the quality assurance	0	100
Sub-requirement 4.2.5	Device enclosure complexity: As per supplied enclosure specification subjected to Non-Disclosure Agreement (NDA) – The briefing session will be used to present Device enclosure	Signing of the NDA and the Declaration Form	0	100

		1	T	1
	designs. The dimensions and 3D enclosure files will be shared to attendees during the briefing session.			
Sub-requirement 4.2.6	The enclosure color must be black.	Verify the color of the enclosure to be black	0	100
			<u> </u>	
Requirement 4.4.1		nodule (PCB) must be able to fit in the dimen lle part		
	Technical Criteria	Verification test	Outcome Not Met	Outcome Met
Sub-requirement 4.4.1.1	Power Supply Module PCB is of Surface mount with minimum of double-layer PCB type.	Run PCB Gerber file on Gerber View software	0	100
Sub-requirement 4.4.1.2	PCB Dimensions: 33mm x 33mm x 5mm(LxWxH)	Measure the dimensions using a vernier calliper	0	100
Sub-requirement 4.4.1.3	PCB Mounting: Corner mounted with (6mm x 3mm) head screws measured 28mm from the centre of the screw holes.	Place the Power Supply Module PCB inside the bottom handle and it must fit in the screw positions	0	100
Sub-requirement 4.4.1.4	PCB Complexity: Solder Masking, minimum of double-layer and silk screening	Run PCB Gerber file on Gerber View software	0	100
Sub-requirement 4.4.1.5	Quality: IPC Class II specification.	Supplier must provide a manufacturing report or certificate for quality assurance	0	100
Sub-requirement 4.4.1.6	micro-USB connector positioned to fit as described in the Step file (body fingerprint scanner Bottom Step file).	Inserting the Power Supply Module PCB inside the Device bottom handle with the USB positioned to the	0	100

	1	connector		1			
		connector					
		opening.					
Poquiromont	The newer supply m	andula must ha abla t	o ho poworod				
Requirement 4.4.2		The power supply module must be able to be powered from the Lithium-lon battery and a 5V/2A DC source.					
4.4.2	Technical Criteria						
			Met	Outcome met			
Sub-requirement 4.4.2.1	The power supply module must be able to be powered by a Lithium-lon Battery with maximum dimensions of 70mm x 60mm x 10mm. (LxWxH)	Connect a Lithium- lon Battery to the Power Supply Module and fit them inside the bottom handle space.	0	100			
Sub-requirement 4.4.2.2	The power supply module must be able to be powered by the DC Source rated at 5V/2A with a micro-USB output connector.	Connect a micro- USB DC source to the Power Supply Module placed inside the enclosure bottom handle space.	0	100			
Sub-requirement 4.4.2.3	The power supply module must have status indicator for battery charging and fully charged status when the 5V/2A DC source is connected.	Connect the DC source to the power supply module placed inside the enclosure bottom handle space and should be able to see the status indicators through the micro-USB connector opening.	0	100			
De ausire es es t	The province	and the message Co	4				
Requirement 4.4.3	The power supply module must incorporate a powerpath controller for power switchover between a battery and a 5V DC source when powering the Device.						
	Technical Criteria	Verification test	Outcome Not met	Outcome met			
Sub-requirement 4.4.3.1	The Device must power ON when the Lithium-lon Battery is plugged into the power supply module.	Insert the Pi OS SD card and Press Button 1 (Power Button), then the Device LCD must indicate the Pi	0	100			

		Booting stage and after show the Pi home screen. The Device must be able to perform and sustain the Device acceptance tests.		
1Sub-requirement 4.4.3.2	The Device must power ON from the DC source (5V/2A) when connected to the power supply module even when the battery is connected to the power supply module.	Insert the Pi OS SD card into the Pi board and Press Button 1 (Power Button), then the Device LCD must indicate the Pi Booting stage and after show the Pi home screen. The Device must be able to perform and sustain the Device acceptance tests.	0	100
Sub-requirement 4.4.3.3	The power supply module must be able to charge the battery while powering the Device from the 5V DC source.	Load the Device Test application and Press Button 1 (Power Button), then on the Test application screen the battery indicator must show that it is charging by increasing the battery percentage	0	100
Sub-requirement 4.4.3.4	The power module circuit must be able to track the Lithium-Ion battery level and communicated this through an I2C interface.	Load the Device Test application and Press Button 1 (Power Button), then on the Test application screen the battery indicator must show that it is charging	0	100

Sub-requirement 4.4.3.5	The power supply module must incorporate a battery charger capability that will charge the battery when the input power is from the 5V DC source.	Load the Device Test application and Press Button 1 (Power Button), then on the Test application screen the battery indicator must show that it is charging	0	100
Requirement	ed with			
4.4.4	documentation. Technical Criteria	Verification test	Outcome Not Met	Met
Sub-requirement 4.4.4.1	The power supply module shall contain datasheets for all components including the battery, PCB binary files, and circuit diagrams.	Provide a documentation report for the power supply module together with datasheets for the BOM, Schematic Diagram for the Power Supply Module and Gerber Files for the PCB.	0	100
Requirement 4.5	Perform the followin expected results as	g system acceptance outlined in table 1	tests to the	
	Technical Criteria	Verification test	Outcome Not met	Outcome met
Sub-requirement 4.5.1	Test report outlining the test cases (as per table 1) outcome results.	Test caseID1 scenario	0	Test report addressing the mentioned expected results
		Test caseID2 scenario	0	100 Test report addressing the mentioned expected results

Test caseID3 scenario	0	100 Test report addressing the mentioned expected results
Test caseID4 scenario	0	100 Test report addressing the mentioned expected results
Test caseID5 scenario	0	100 Test report addressing the mentioned expected results

Proposals with functionality/technical points of less than the pre-determined minimum overall percentage of 100% on any of the individual criteria will be eliminated from further evaluation. It is critical for **all** the components of the Device mentioned above to function in order to meet our minimum requirements.

5.2 Refer to Annexure A for the scoring sheet that will be used to evaluate functionality.

6 ELIMINATION CRITERIA

Proposals will be eliminated under the following conditions:

- Submission after the deadline;
- Proposals submitted at the incorrect email address
- Incomplete proposal submission
- National Treasury Restricted suppliers
- Failure to submit fully completed and signed SBD 4 and SBD 1.
- Non-attendance of the compulsory briefing session

7 NATIONAL TREASURY CENTRAL SUPPLIER DATABASE REGISTRATION

Before any negotiations will start with the winning bidder it will be required from the winning bidder to:

- be registered on National Treasury's Central Supplier Database (CSD). Registrations can be completed online at: www.csd.gov.za;
- provide the CSIR of their CSD registration number; and
- provide the CSIR with a certified copy of their B-BBEE certificate. If no certificate can be provided, no points will be scored during the evaluation process. (RSA suppliers only)

SECTION B - TERMS AND CONDITIONS

8 VENUE FOR PROPOSAL SUBMISSION

All proposals must be submitted at the following email address: tender@csir.co.za

9 TENDER PROGRAMME

The tender program, as currently envisaged, incorporates the following key dates:

Issue of tender documents: 01 September 2022
 Compulsory briefing session / site inspection etc: 05 September 2022
 Last date for submission of queries: 09 September 2022
 Closing / submission Date: 16 September 2022

10 SUBMISSION OF PROPOSALS

10.1 Proposals must consist of two parts, each of which is placed in a separate sealed package clearly marked:

PART 1: Technical Proposal: RFP No-1028-16-09-2022

PART 2: Pricing Proposal, B-BBEE and other Mandatory Documentation:

RFP No -1028-16-09-2022

- 10.2 Proposals submitted by companies must be signed by a person or persons duly authorised.
- 10.3 The CSIR will award the contract to qualified tenderer(s)' whose proposal is determined to be the most advantageous to the CSIR, taking into consideration the technical (functional) solution, price and B-BBEE.

11 DEADLINE FOR SUBMISSION

Proposals shall be submitted at the address mentioned above no later than the closing date of **Friday, 16 September 2022** during CSIR's business hours. The CSIR business hours are between 08h00 and 16h30.

Where a proposal is not received by the CSIR by the due date and stipulated place, it will be regarded as a late tender. Late tenders will not be considered.

12 AWARDING OF TENDERS

12.1 Awarding of tenders will be published on the National Treasury e-tender portal or the CSIR's tender website. No regret letters will be sent out.

13 EVALUATION PROCESS

13.1 Evaluation of proposals

All proposals will be evaluated by an evaluation team for functionality, price and B-BBEE. Based on the results of the evaluation process and upon successful negotiations, the CSIR will approve the awarding of the contract to successful tenderers.

A two-phase evaluation process will be followed.

- The first phase includes evaluation of elimination and functionality criteria.
- The second phase includes the evaluation of price and B-BBEE status.

Pricing Proposals will only be considered after functionality phase has been adjudicated and accepted. Only proposals that achieved the specified minimum qualification scores for functionality will be evaluated further using the preference points system.

13.2 Preference points system

The 80/20 preference point system will be used where 80 points will be dedicated to price and 20 points to B-BBEE status. If all tenders received are more than R50m, the proposal will be cancelled and re-issued.

14 PRICING PROPOSAL

- 14.1 Pricing proposal must be cross-referenced to the sections in the Technical Proposal. Any options offered must be clearly labelled. Separate pricing must be provided for each option offered to ensure that pricing comparisons are clear and unambiguous.
- 14.2 Price needs to be provided in South African Rand (excl. VAT), with details on price elements that are subject to escalation and exchange rate fluctuations clearly indicated.
- 14.3 Price should include additional cost elements such as freight, insurance until acceptance, duty where applicable.

14.4 Only firm prices* will be accepted during the tender validity period. Non–firm prices** (including prices subject to rates of exchange variations) will not be considered.

*Firm price is the price that is only subject to adjustments in accordance with the actual increase or decrease resulting from the change, imposition, or abolition of customs or excise duty and any other duty, levy, or tax which, in terms of a law or regulation is binding on the contractor and demonstrably has an influence on the price of any supplies, or the rendering costs of any service, for the execution of the contract;

**Non-firm price is all prices other than "firm" prices.

14.5 Payment will be according to the CSIR Payment Terms and Conditions.

15 VALIDITY PERIOD OF PROPOSAL

Each **proposal** shall be valid for a minimum period of three (3) months calculated from the closing date.

16 APPOINTMENT OF SERVICE PROVIDER

- 16.1 The contract will be awarded to the tenderer who scores the highest total number of points during the evaluation process, except where the law permits otherwise.
- 16.2 Appointment as a successful service provider shall be subject to the parties agreeing to mutually acceptable contractual terms and conditions. In the event of the parties failing to reach such agreement CSIR reserves the right to appoint an alternative supplier.
- 16.3 Awarding of contracts will be announced on the National Treasury website and no regret letters will be sent to unsuccessful bidders.

17 ENQUIRIES AND CONTACT WITH THE CSIR

Any enquiry regarding this RFP shall be submitted in writing to CSIR at tender@csir.co.za with "RFP No 1028/16/09/2022 - The provision or supply of Manufacturing of the Fingerprint Recognition Device to CSIR" as the subject.

Any other contact with CSIR personnel involved in this tender is not permitted during the RFP process other than as required through existing service arrangements or as requested by the CSIR as part of the RFP process.

18 MEDIUM OF COMMUNICATION

All documentation submitted in response to this RFP must be in English.

19 COST OF PROPOSAL

Tenderers are expected to fully acquaint themselves with the conditions, requirements and specifications of this RFP before submitting proposals. Each tenderer assumes all risks for resource commitment and expenses, direct or indirect, of proposal preparation and participation throughout the RFP process. The CSIR is not responsible directly or indirectly for any costs incurred by tenderers.

20 CORRECTNESS OF RESPONSES

- 20.1 The tenderer must confirm satisfaction regarding the correctness and validity of their proposal and that all prices and rates quoted cover all the work/items specified in the RFP. The prices and rates quoted must cover all obligations under any resulting contract.
- 20.2 The tenderer accepts that any mistakes regarding prices and calculations will be at their own risk.

21 VERIFICATION OF DOCUMENTS

- 21.1 No liability will be accepted by the CSIR in regard to anything arising from the fact that pages are missing or duplicated.
- 21.2 Pricing schedule and B-BBEE credentials should be submitted with the proposal, but as a separate document and no such information should be available in the technical proposal.

22 SUB-CONTRACTING

22.1 A tenderer will not be awarded points for B-BBEE status level if it is indicated in the tender documents that such a tenderer intends sub-contracting more than 25% of the value of the contract to any other enterprise that does not qualify for at least the points that such a

- tenderer qualifies for, unless the intended sub-contractor is an exempted micro enterprise that has the capability and ability to execute the sub-contract.
- 22.2 A tenderer awarded a contract may not sub-contract more than 25% of the value of the contract to any other enterprise that does not have an equal or higher B-BBEE status level than the person concerned, unless the contract is sub-contracted to an exempted micro enterprise that has the capability and ability to execute the sub-contract.

23 ENGAGEMENT OF CONSULTANTS

The consultants will only be remunerated at the rates:

- 23.1 Determined in the "Guideline for fees", issued by the South African Institute of Chartered Accountants (SAICA); or
- 23.2 Set out in the "Guide on Hourly Fee Rates for Consultants", by the Department of Public Service and Administration (DPSA); or
- 23.3 Prescribed by the body regulating the profession of the consultant.

24 TRAVEL EXPENSES

- 24.1 All travel expenses for the CSIR's account, be it directly via the CSIR's travel agent or indirectly via re-imbursements, must be in line with the CSIR's travel policy. The following will apply:
- 24.1.1 Only economy class tickets will be used.
- 24.1.2 A maximum of R1400 per night for accommodation, dinner, breakfast and parking will be allowed.
- 24.1.3 No car rentals of more than a Group B will be accommodated.

25 ADDITIONAL TERMS AND CONDITIONS

- 25.1 A tenderer shall not assume that information and/or documents supplied to CSIR, at any time prior to this request, are still available to CSIR, and shall consequently not make any reference to such information document in its response to this request.
- 25.2 Copies of any affiliations, memberships and/or accreditations that support your submission must be included in the tender.
- 25.3 In case of proposal from a joint venture, the following must be submitted together with the proposal:

- Joint venture Agreement including split of work signed by both parties;
- The original or certified copy of the B-BBEE certificate of the joint venture;
- The Tax Clearance Certificate of each joint venture member;
- Proof of ownership/shareholder certificates/copies; and
- Company registration certificates.
- 25.4 An omission to disclose material information, a factual inaccuracy, and/or a misrepresentation of fact may result in the disqualification of a tender, or cancellation of any subsequent contract.
- 25.5 Failure to comply with any of the terms and conditions as set out in this document will invalidate the Proposal.

26 CSIR RESERVES THE RIGHT TO

- 26.1 Extend the closing date;
- 26.2 Verify any information contained in a proposal;
- 26.3 Request documentary proof regarding any tendering issue;
- 26.4 Give preference to locally manufactured goods;
- 26.5 Appoint one or more service providers, separately or jointly (whether or not they submitted a joint proposal);
- 26.6 Award this RFP as a whole or in part;
- 26.7 Cancel or withdraw this RFP as a whole or in part.

27 DISCLAIMER

This RFP is a request for proposals only and not an offer document. Answers to this RFP must not be construed as acceptance of an offer or imply the existence of a contract between the parties. By submission of its proposal, tenderers shall be deemed to have satisfied themselves with and to have accepted all Terms & Conditions of this RFP. The CSIR makes no representation, warranty, assurance, guarantee or endorsements to tenderer concerning the RFP, whether with regard to its accuracy, completeness or otherwise and the CSIR shall have no liability towards the tenderer or any other party in connection therewith.

DECLARATION BY TENDERER

Only tenderers who completed the declaration below will be considered for evaluation.

RFP No: 1028/16/09/2022

I hereby undertake to render services described in the attached tendering documents to CSIR in accordance with the requirements and task directives/proposal specifications stipulated in RFP No 1028/16/09/2022 at the price/s quoted. My offer/s remains binding upon me and open for acceptance by the CSIR during the validity period indicated and calculated from the closing date

of the proposal.

I confirm that I am satisfied with regards to the correctness and validity of my proposal; that the price(s) and rate(s) quoted cover all the services specified in the proposal documents; that the price(s) and rate(s) cover all my obligations and I accept that any mistakes regarding price(s) and

rate(s) and calculations will be at my own risk.

I accept full responsibility for the proper execution and fulfilment of all obligations and conditions devolving on me under this proposal as the principal liable for the due fulfilment of this proposal.

I declare that I have no participation in any collusive practices with any tenderer or any other person regarding this or any other proposal.

I accept that the CSIR may take appropriate actions, deemed necessary, should there be a conflict of interest or if this declaration proves to be false.

I confirm that I am duly authorised to sign this proposal.

NAME (PRINT)	
(WITNESSES
CAPACITY	
2.2	1
SIGNATURE	2
NAME OF FIRM	2
	DATE:
DATE	